

Tribocomp® PA66 LGF30 TS0 S8 polyamide 66

Tribocomp® PA66 LGF30 TS0 S8, is a 30% long glass fiber reinforced, black, high-flow PA66 compound containing 15% PTFE and having excellent

tribological performance. It can easily be processed on most injection molding machines.

General

Material Status	 Commercial: Active 			
Availability	Africa & Middle EastAsia PacificEurope	le East • Latin America • North America		
Filler / Reinforcement	 Long Glass Fiber, 30% Filler by Weight 	• PTFE, 15% Filler by Weight		
Features	Abrasion ResistantHeat StabilizedHigh Flow	High FrictionHigh Temperature StrengthLow Shrinkage		
Uses	Automotive ApplicationsAutomotive Under the HoodEngineering Parts	GearsIndustrial ApplicationsPower/Other Tools		
RoHS Compliance	 RoHS Compliant 			
Appearance	• Black			
Forms	 Pellets 			
Processing Method	Compression Molding	 Injection Molding 		
Physical	Dry	Conditioned Unit	Test method	
Density	1.50	g/cm³	ISO 1183	
Molding Shrinkage - Flow	0.40	%	ISO 294-4	
Water Absorption (Equilibrium, 23°C, 50% RH)	1.4	%	ISO 62	
Mechanical	Dry	Conditioned Unit	Test method	
Tensile Modulus			ISO 527-1	
23°C	10500	8000 MPa		
90°C	6600	MPa		
Tensile Stress			ISO 527-2	
Break, 23°C	195	145 MPa		
Break, 90°C	125	MPa		
Tensile Strain			ISO 527-2	
Yield, 23°C	3.0	%		
Break, 23°C		2.0 %		
Flexural Modulus (23°C)	10200	MPa	ISO 178	
Flexural Stress (23°C)	285	MPa	ISO 178	

Mechanical		Dry	Conditioned Unit	Test method	
Coefficient of Friction		,		ASTM D3702	
Dynamic		0.23			
Static		0.18			
Wear Factor		13.0		ASTM D3702	
Impact		Dry	Conditioned Unit	Test method	
Charpy Notched Impact 9 (23°C)	Strength	20	kJ/m²	ISO 179	
Charpy Unnotched Impac (23°C)	ct Strength	70	kJ/m²	ISO 179	
Thermal		Dry	Conditioned Unit	Test method	
Deflection Temperature U	Inder Load				
0.45 MPa, Unannealed		262	°C	ISO 75-2/B	
1.8 MPa, Unannealed		258	°C	ISO 75-2/A	
Thermal Conductivity		0.29	W/m/K	ISO 22007	
Coefficient of Linear Therr Expansion	mal	2.9E-5	cm/cm/°C	ISO 11359-2	
Electrical		Dry	Conditioned Unit	Test method	
Electric Strength (2.00 mr	n)	35	kV/mm	IEC 60243-1	
Comparative Tracking Inc	dex	500	V	IEC 60112	
Surface Resistivity		1.0E+12	ohms/sq	ASTM D257	
Additional Information					
Dry	The value listed a with S.O.P. method		ge ISO 294-4, was tested in ac	cordance	
Injection			Dry Unit		
Drying Temperature	80 to 100 °C				
Drying Time	4.0 hr				
Suggested Max Moisture	0.10 %				
Rear Temperature	290 to 300 °C				
Middle Temperature	300 °C				
Front Temperature	300 °C				
Nozzle Temperature		300 °C			
·			300 C		
Processing (Melt) Temp			< 300 °C		
Mold Temperature					

Injection Notes

Pre-drying -- Since polyamides are hygroscopic materials as well as sensitive to moisture during processing, this product should always be pre-dried.

Regrind -- Regrind of highly filled thermoplastic materials, such as this material, should only be recycled with special care. The regrind content must never exceed 15%, and only regrind of optimum quality should be used. In any case, part properties should be checked.

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Notes

Typical properties: these are not to be construed as specifications.

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